

Si APD

S15415 series

High-speed, compact Si APD that does not require temperature adjustment

The S15415 series is a gain-stabilized APD (GS APD) with a built-in temperature compensation function inside the sensor. This realizes constant gain without the need for temperature adjustment. It is suitable for laser monitors of optical rangefinders used in a wide range of applications, from consumer to industrial.

Features

- Built-in temperature compensation function
- **■** Compact package: 2.0 × 1.8 × 0.85^t mm
- Peak sensitivity wavelength: 840 nm (M=50)
- ➡ High-speed response: Cutoff frequency=500 MHz typ.

(λ=905 nm, M=50)

Applications

Optical rangefinders

Structure

| Parameter | S15415-02 | S15415-05 | Unit |
|-----------------------|----------------|-----------|------|
| Photosensitive area*1 | ф0.2 | φ0.5 | mm |
| Package | Glass epoxy | | |
| Seal material | Silicone resin | | |

^{*1:} Area in which a typical gain can be obtained

■ Absolute maximum ratings

| Parameter | Symbol | Specification | |
|----------------------------|--------------|-----------------|----|
| Anode reverse current (DC) | IR anode max | 0.1 | mA |
| Forward current | IF max | 10 | mA |
| Operating temperature*2 | Topr | -30 to +105 | °C |
| Storage temperature*2 | Tstg | -40 to +105 | °C |
| Soldering temperature | Tsol | 260 (3 times)*3 | °C |

^{*2:} No dew condensation

When there is a temperature difference between a product and the surrounding area in high humidity environments, dew condensation may occur on the product surface. Dew condensation on the product may cause deterioration in characteristics and reliability.

Note: Exceeding the absolute maximum ratings even momentarily may cause a drop in product quality. Always be sure to use the product within the absolute maximum ratings.

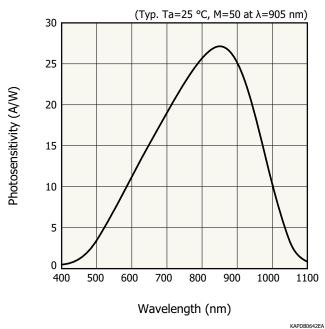
^{*3:} Reflow soldering, JEDEC J-STD-020 MSL 2a, see P.5

■ Electrical and optical characteristics (Ta=25 °C, unless otherwise noted)

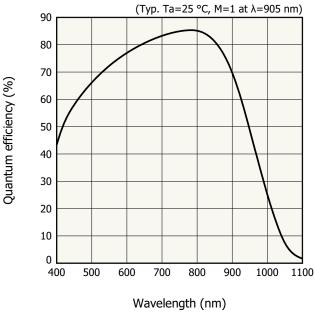
| Dayamatar | Symbol Condition | | S15415-02 | | S15415-05 | | l lmit | | |
|--|------------------|--|--------------------------------|-----------|-----------|--------------------------------|-----------|------|----------|
| Parameter | Symbol | Condition | | Тур. | Max. | Min. | Тур. | Max. | Unit |
| Spectral response range | λ | | | | 400 to | 1100 | | | nm |
| Peak sensitivity wavelength | λр | | - | 840 | - | - | 840 | - | nm |
| Photosensitivity | S | λ=905 nm, M=1 | - | 0.5 | - | - | 0.5 | - | A/W |
| Quantum efficiency | QE | λ=905 nm, M=1 | - | 70 | - | - | 70 | - | % |
| Operating reverse voltage | Vop | Gain-stabilized mode operation*4 | 185 + 1.1 × (Ta opr - 25)*5 | - | - | 185 + 1.1 × (Ta opr - 25)*5 | - | - | V |
| Temperature coefficient of operating reverse voltage | ΔTVop | | - | 1.1 | - | - | 1.1 | - | V/°C |
| Dark current | ID | Gain-stabilized mode operation*4 | - | 20 | 200 | - | 40 | 400 | pА |
| Dark current temperature coefficient | ΔTid | M=50 | - | 1.1 | - | - | 1.1 | - | times/°C |
| Cutoff frequency | fc | M=50, RL=50 Ω λ=905 nm, -3 dB | - | 500 | - | - | 500 | - | MHz |
| Terminal capacitance | Ct | M=50, f=1 MHz | - | 0.5 | - | - | 1.1 | - | pF |
| Excess noise figure | Х | M=50, λ=905 nm | - | 0.3 | - | - | 0.3 | - | - |
| Gain | М | Gain-stabilized mode operation*4, λ=905 nm | 40 | 50 | 60 | 40 | 50 | 60 | - |
| Gain control range | _ | λ=905 nm | - | 30 to 100 | - | - | 30 to 100 | - | - |

^{*4:} Apply bias voltage to anode. IR anode limit=10 μA , guard pin=GND

Spectral response



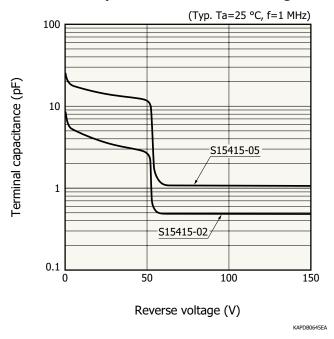
- Quantum efficiency vs. wavelength



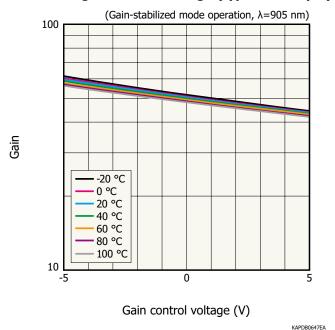
KAPDB0643EA

^{*5:} Ta opr=assumed maximum operating temperature (°C)

Terminal capacitance vs. reverse voltage

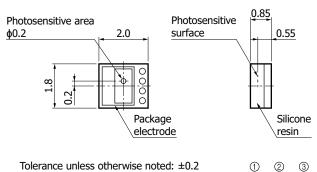


Gain vs. gain control voltage (typical example)

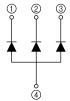


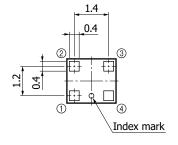
Dimensional outlines (unit: mm)

S15415-02



Tolerance unless otherwise noted: ± 0.2 Chip position accuracy with respect to package electrode pattern center: X, Y $\leq \pm 0.2$

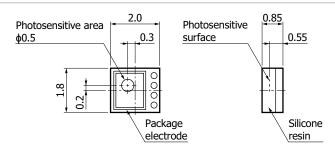


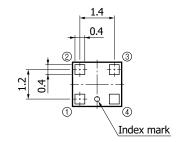


| 1 1 | Gain control | Gain control voltage input (connect to GND) |
|-----|--------------|---|
| 2 | Output | APD output |
| 3 | Guard | Leakage current output (connect to GND) |
| 4 | Anode | Bias voltage input |

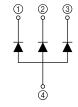
KAPDA0229E/

S15415-05





Tolerance unless otherwise noted: ± 0.2 Chip position accuracy with respect to package electrode pattern center: X, Y $\leq \pm 0.2$



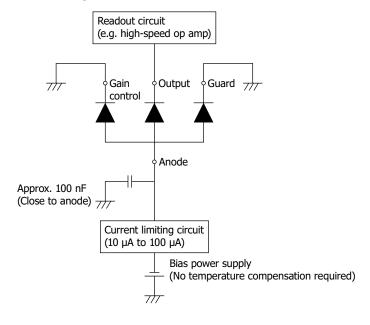
| 1 | Gain control | Gain control voltage input (connect to GND) |
|---|--------------|---|
| 2 | Output | APD output |
| 3 | Guard | Leakage current output (connect to GND) |
| 4 | Anode | Bias voltage input |

KAPDA0230EA

Recommended land pattern

1.4 0.4

- Connection example



- \cdot Connection to a bias power supply and a current limiting circuit are essential.
- The gain can be controlled by applying a voltage to the gain pin.
- · We recommend connecting a capacitor near the anode pin to stabilize the bias voltage.

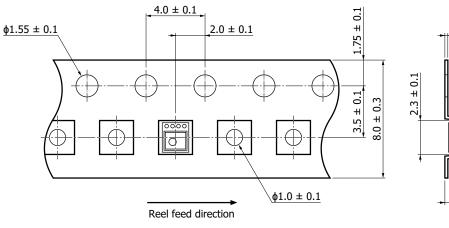
KAPDC0137EB

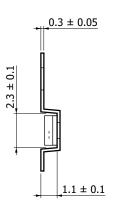
Standard packing specifications

■ Reel (conforms to JEITA ET-7200)

| Appearance | Hub diameter | Tape width | Material | Electrostatic characteristics |
|------------|--------------|------------|----------|-------------------------------|
| φ180 mm | ф60 mm | 8 mm | PS | Conductive |

■ Embossed tape (unit: mm, material: PS, conductive)



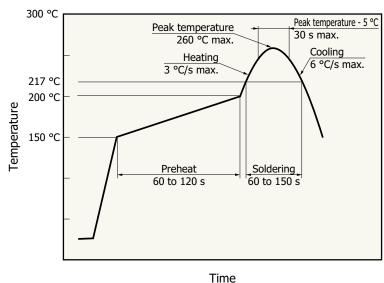


KAPDC0139EA

- Packing quantity 1000 pcs/reel
- Packing state

 Reel and desiccant in moisture-proof packaging (vacuum-sealed)

Recommended reflow soldering conditions



- After unpacking, store in an environment at a temperature of 30 °C or less and a humidity of 60% or less, and perform reflow soldering within 4 weeks.
- The effect that the product receives during reflow soldering varies depending on the circuit board and reflow oven that are used. When you set reflow soldering conditions, check that problems do not occur in the product by testing out the conditions in advance.

KMPDB0405EC

S15415 series

Baking

If 12 months have passed without unpacking or the above storage period has passed after unpacking, perform baking before reflow soldering to dehumidify. For the baking, refer to "Precautions / Surface mount type products" in the related information.

- Recommended baking conditions
- · Temperature: 150 °C, 3 hours, up to twice

Note: When you set baking conditions, check that problems do not occur in the product by testing out the conditions in advance.

Related products

Photosensor with front-end IC S16429 series



This device is for direct TOF (time-of-flight) distance measurement, integrating the S15415 series and a transimpedance amplifier. It offers low-noise and high-speed response.

Features

- Stable gain against temperature fluctuations
- No gain adjustment according to individual differences required
- → High-speed response
- **Low noise**

| Type no. | Built-in element | Cutoff frequency |
|-------------|------------------|------------------|
| S16429-01CT | S15415-02 | 300 MHz |
| S16429-02CT | S15415-05 | 280 MHz |

Related information

www.hamamatsu.com/sp/ssd/doc_en.html

- Precautions
- Disclaimer
- · Precautions / Surface mount type products
- Catalogs
- · Technical note / Si APD

The content of this document is current as of February 2025.

Product specifications are subject to change without prior notice due to improvements or other reasons. This document has been carefully prepared and the information contained is believed to be accurate. In rare cases, however, there may be inaccuracies such as text errors. Before using these products, always contact us for the delivery specification sheet to check the latest specifications.

The product warranty is valid for one year after delivery and is limited to product repair or replacement for defects discovered and reported to us within that one year period. However, even if within the warranty period we accept absolutely no liability for any loss caused by natural disasters or improper product use. Copying or reprinting the contents described in this material in whole or in part is prohibited without our prior permission.

AMAMATSU

www.hamamatsu.com

HAMAMATSU PHOTONICS K.K., Solid State Division

1126-1 Ichino-cho, Chuo-ku, Hamamatsu City, 435-8558 Japan, Telephone: (81)53-434-3311, Fax: (81)53-434-5184

LOSA: HAMAMATSU CORPORATION: 360 Footbill Road, Bridgewater, NJ 08807, U.S.A.; Telephone: (1)908 231 0960, Fax: (1)908 231 1218

Germany: HAMAMATSU CORPORATION: 360 Footbill Road, Bridgewater, NJ 08807, U.S.A.; Telephone: (1)908 231 0960, Fax: (1)908 231 1218

Germany: HAMAMATSU PHOTONICS DEUTSCHLAND GMBH: Arzbergerstr. 10, 82211 Herrsching am Ammersee, Germany, Telephone: (49)8152 375 0, Fax: (49)8152 265 8 E mail: info@hamamatsu.de

France: HAMAMATSU PHOTONICS FRANCE S.A.R.L.: 19 Rue du Saule Trapu, Parc du Moulin de Massy, 91882 Massy Cedex, France, Telephone: (33)1 69 53 71 00, Fax: (33)1 69 53 71 00, Fax: (34)1 10 E mail: info@hamamatsu.fr

United Kingdom: HAMAMATSU PHOTONICS UK LIMITED: 2 Howard Count,10 Tewin Road, Welwyn Garden City, Hertfordshire, AJ7 18W, UK, Telephone: (44)107 928777 E mail: info@hamamatsu.co.uk

North Europe: HAMAMATSU PHOTONICS ONDEDN AB: Torshamnsgatan 35, 16440 Kista, Sweden, Telephone: (46)8 509 031 00, Fax: (46)8 509 031 01 E mail: info@hamamatsu.se

Italy: HAMAMATSU PHOTONICS (TAILA S.R.L.: Strada della Moia, 1 int. 6 20044 Arese (Milano), Italy, Telephone: (49)02 93 58 17 33, Fax: (39)02 93 58 17 41 E mail: info@hamamatsu.it

China: HAMAMATSU PHOTONICS (CHINA) CO, LTD.: 1201, Tower B, Jiaming Center, 27 Dongsanhuan Beilu, Chaoyang District, 100020 Beijing, PR. China, Telephone: (86)10 6586 6006, Fax: (86)10 6586 6006, Fax